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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 6x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c773t-i-ss

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Corrections to this Data Sheet

We constantly strive to improve the quality of all our products and documentation. We have spent a great deal of time to ensure that this document is correct. However, we realize that we may have missed a few things. If you find any information that is missing or appears in error, please:

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TABLE 1-2 PIC16C774 PINOUT DESCRIPTION (Cont.'d)

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	I/O/P Type	Buffer Type	Description
						PORTC is a bi-directional I/O port.
RC0/T1OSO/T1CKI	15	16	32	I/O	ST	RC0 can also be the Timer1 oscillator output or a Timer1 clock input.
RC1/T1OSI/CCP2	16	18	35	I/O	ST	RC1 can also be the Timer1 oscillator input or Capture2 input/Compare2 output/PWM2 output.
RC2/CCP1	17	19	36	I/O	ST	RC2 can also be the Capture1 input/Compare1 output/PWM1 output.
RC3/SCK/SCL	18	20	37	I/O	ST	RC3 can also be the synchronous serial clock input/output for both SPI and I^2C modes.
RC4/SDI/SDA	23	25	42	I/O	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I^2C mode).
RC5/SDO	24	26	43	I/O	ST	RC5 can also be the SPI Data Out (SPI mode).
RC6/TX/CK	25	27	44	I/O	ST	RC6 can also be the USART Asynchronous Transmit or Synchronous Clock.
RC7/RX/DT	26	29	1	I/O	ST	RC7 can also be the USART Asynchronous Receive or Synchronous Data.
						PORTD is a bi-directional I/O port or parallel slave port when interfacing to a microprocessor bus.
RD0/PSP0	19	21	38	I/O	ST/TTL(3)	
RD1/PSP1	20	22	39	I/O	ST/TTL(3)	
RD2/PSP2	21	23	40	I/O	ST/TTL(3)	
RD3/PSP3	22	24	41	I/O	ST/TTL(3)	
RD4/PSP4	27	30	2	I/O	ST/TTL(3)	
RD5/PSP5	28	31	3	I/O	ST/TTL(3)	
RD6/PSP6	29	32	4	I/O	ST/TTL(3)	
RD7/PSP7	30	33	5	I/O	ST/TTL(3)	
						PORTE is a bi-directional I/O port.
RE0/$\overline{RD}$/AN5	8	9	25	I/O	ST/TTL(3)	RE0 can also be read control for the parallel slave port, or analog input5.
RE1/$\overline{WR}$/AN6	9	10	26	I/O	ST/TTL(3)	RE1 can also be write control for the parallel slave port, or analog input6.
RE2/$\overline{CS}$/AN7	10	11	27	I/O	ST/TTL(3)	RE2 can also be select control for the parallel slave port, or analog input7.
AVss	12	13	29	P		Ground reference for A/D converter
AVDD	11	12	28	P		Positive supply for A/D converter
VSS	31	34	6	P	—	Ground reference for logic and I/O pins.
VDD	32	35	7	P	—	Positive supply for logic and I/O pins.
NC	—	1,17,28, 40	12,13, 33,34		—	These pins are not internally connected. These pins should be left unconnected.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured for the multiplexed function.
2: This buffer is a Schmitt Trigger input when used in serial programming mode.
3: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).
4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

2.0 MEMORY ORGANIZATION

There are two memory blocks in each of these PICmicro® microcontrollers. Each block (Program Memory and Data Memory) has its own bus so that concurrent access can occur.

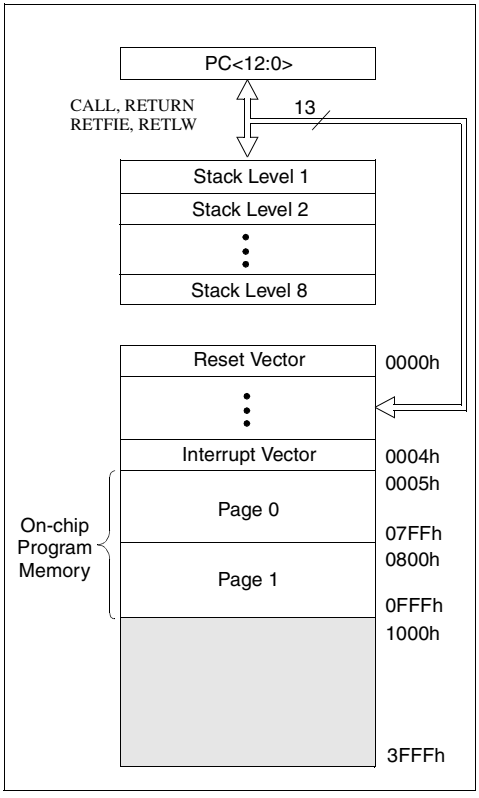
Additional information on device memory may be found in the PICmicro™ Mid-Range Reference Manual, (DS33023).

2.1 Program Memory Organization

The PIC16C77X PICmicros have a 13-bit program counter capable of addressing an 8K x 14 program memory space. Each device has 4K x 14 words of program memory. Accessing a location above the physically implemented address will cause a wraparound.

The reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK



2.2 Data Memory Organization

The data memory is partitioned into multiple banks which contain the General Purpose Registers and the Special Function Registers. Bits RP1 and RP0 are the bank select bits.

RP1	RP0

(STATUS<6:5>)

= 00 → Bank0
= 01 → Bank1
= 10 → Bank2
= 11 → Bank3

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM. All implemented banks contain special function registers. Some “high use” special function registers from one bank may be mirrored in another bank for code reduction and quicker access.

2.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly, or indirectly through the File Select Register FSR.

2.2.2.1 STATUS REGISTER

The STATUS register, shown in Figure 2-3, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper-three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions, not affecting any status bits, see the "Instruction Set Summary."

Note 1: The C and DC bits operate as a $\overline{borrow}$ and $\overline{digit\ borrow}$ bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

FIGURE 2-3: STATUS REGISTER (ADDRESS 03h, 83h, 103h, 183h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **IRP**: Register Bank Select bit (used for indirect addressing)
1 = Bank 2, 3 (100h - 1FFh)
0 = Bank 0, 1 (00h - FFh)

bit 6-5: **RP1:RP0**: Register Bank Select bits (used for direct addressing)
`11` = Bank 3 (180h - 1FFh)
`10` = Bank 2 (100h - 17Fh)
`01` = Bank 1 (80h - FFh)
`00` = Bank 0 (00h - 7Fh)
Each bank is 128 bytes

bit 4: **$\overline{TO}$**: Time-out bit
1 = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
0 = A WDT time-out occurred

bit 3: **$\overline{PD}$**: Power-down bit
1 = After power-up or by the `CLRWDT` instruction
0 = By execution of the `SLEEP` instruction

bit 2: **Z**: Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1: **DC**: Digit carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions) (for $\overline{borrow}$ the polarity is reversed)
1 = A carry-out from the 4th low order bit of the result occurred
0 = No carry-out from the 4th low order bit of the result

bit 0: **C**: Carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
1 = A carry-out from the most significant bit of the result occurred
0 = No carry-out from the most significant bit of the result occurred
Note: For $\overline{borrow}$ the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

3.2 PORTB and the TRISB Register

PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is TRISB. Setting a TRISB bit (=1) will make the corresponding PORTB pin an input, i.e., put the corresponding output driver in a hi-impedance mode. Clearing a TRISB bit (=0) will make the corresponding PORTB pin an output, i.e., put the contents of the output latch on the selected pin.

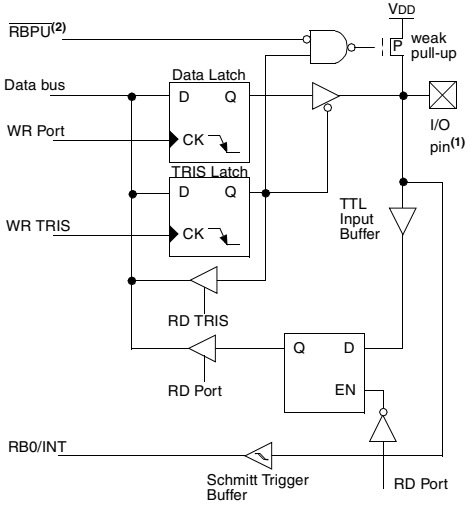
EXAMPLE 3-1: INITIALIZING PORTB

```
BCF     STATUS, RP0  ;
CLRF    PORTB        ; Initialize PORTB by
                     ; clearing output
                     ; data latches
BSF     STATUS, RP0  ; Select Bank 1
MOVLW   0xCF         ; Value used to
                     ; initialize data
                     ; direction
MOVWF   TRISB        ; Set RB<3:0> as inputs
                     ; RB<5:4> as outputs
                     ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{\text{RBPU}}$ (OPTION_REG<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

The RB0 pin is multiplexed with the external interrupt (RB0/INT).

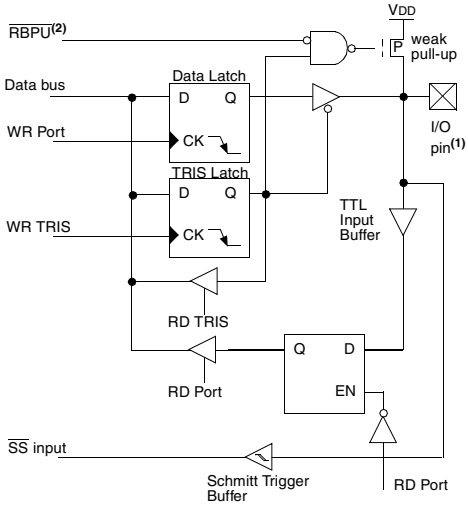
FIGURE 3-4: BLOCK DIAGRAM OF RB0 PIN



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

The RB1 pin is multiplexed with the SSP module slave select (RB1/$\overline{\text{SS}}$).

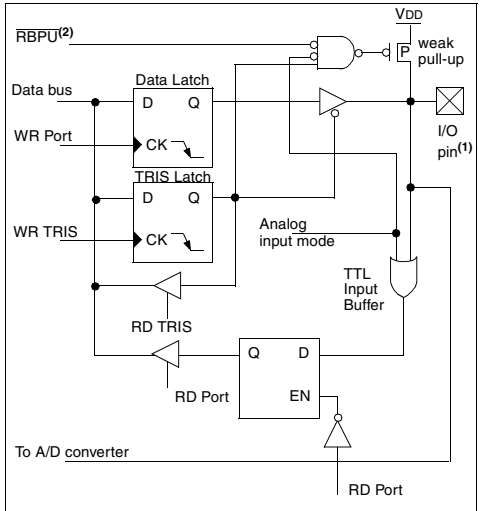
FIGURE 3-5: BLOCK DIAGRAM OF RB1/$\overline{\text{SS}}$ PIN



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

The RB2 pin is multiplexed with analog channel 8 (RB2/AN8).

FIGURE 3-6: BLOCK DIAGRAM OF RB2/AN8 PIN



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

TABLE 3-5 PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input
RC1/T1OSI/CCP2	bit1	ST	Input/output port pin or Timer1 oscillator input or Capture2 input/Compare2 output/PWM2 output
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I^2C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I^2C mode).
RC5/SDO	bit5	ST	Input/output port pin or Synchronous Serial Port data output
RC6/TX/CK	bit6	ST	Input/output port pin or USART Asynchronous transmit or Synchronous clock
RC7/RX/DT	bit7	ST	Input/output port pin or USART Asynchronous receive or Synchronous data

Legend: ST = Schmitt Trigger input

TABLE 3-6 SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
07h	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111

Legend: x = unknown, u = unchanged.

NOTES:

7.0 CAPTURE/COMPARE/PWM (CCP) MODULE(S)

Each CCP (Capture/Compare/PWM) module contains a 16-bit register which can operate as a 16-bit capture register, as a 16-bit compare register or as a PWM master/slave Duty Cycle register. Table 7-1 shows the timer resources of the CCP module modes.

The operation of CCP1 is identical to that of CCP2, with the exception of the special trigger. Therefore, operation of a CCP module in the following sections is described with respect to CCP1.

Table 7-2 shows the interaction of the CCP modules.

CCP1 Module

Capture/Compare/PWM Register1 (CCPR1) is comprised of two 8-bit registers: CCPR1L (low byte) and CCPR1H (high byte). The CCP1CON register controls the operation of CCP1. All are readable and writable.

CCP2 Module

Capture/Compare/PWM Register2 (CCPR2) is comprised of two 8-bit registers: CCPR2L (low byte) and CCPR2H (high byte). The CCP2CON register controls the operation of CCP2. All are readable and writable.

Additional information on the CCP module is available in the PICmicro™ Mid-Range Reference Manual, (DS33023).

TABLE 7-1 CCP MODE - TIMER RESOURCE

CCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

TABLE 7-2 INTERACTION OF TWO CCP MODULES

CCPx Mode	CCPy Mode	Interaction
Capture	Capture	Same TMR1 time-base.
Capture	Compare	The compare should be configured for the special event trigger, which clears TMR1.
Compare	Compare	The compare(s) should be configured for the special event trigger, which clears TMR1.
PWM	PWM	The PWMs will have the same frequency, and update rate (TMR2 interrupt).
PWM	Capture	None
PWM	Compare	None

FIGURE 7-1: CCP1CON REGISTER (ADDRESS 17h) / CCP2CON REGISTER (ADDRESS 1Dh)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CCPxX	CCPxY	CCPxM3	CCPxM2	$\overline{\text{CCPxM1}}$	$\overline{\text{CCPxM0}}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n =Value at POR reset

bit 7-6: **Unimplemented:** Read as '0'

bit 5-4: **CCPxX:CCPxY**: PWM Least Significant bits
Capture Mode: Unused
Compare Mode: Unused
PWM Mode: These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPRxL.

bit 3-0: **CCPxM3:CCPxM0**: CCPx Mode Select bits
0000 = Capture/Compare/PWM off (resets CCPx module)
0100 = Capture mode, every falling edge
0101 = Capture mode, every rising edge
0110 = Capture mode, every 4th rising edge
0111 = Capture mode, every 16th rising edge
1000 = Compare mode, set output on match (CCPxIF bit is set)
1001 = Compare mode, clear output on match (CCPxIF bit is set)
1010 = Compare mode, generate software interrupt on match (CCPxIF bit is set, CCPx pin is unaffected)
1011 = Compare mode, trigger special event (CCPxIF bit is set; CCP1 resets TMR1; CCP2 resets TMR1 and starts an A/D conversion (if A/D module is enabled))
11xx = PWM mode

8.1.5 SLAVE MODE

In slave mode, the data is transmitted and received as the external clock pulses appear on SCK. When the last bit is latched the interrupt flag bit SSPIF (PIR1<3>) is set.

While in slave mode the external clock is supplied by the external clock source on the SCK pin. This external clock must meet the minimum high and low times as specified in the electrical specifications.

While in sleep mode, the slave can transmit/receive data. When a byte is received the device will wake-up from sleep.

8.1.6 SLAVE SELECT SYNCHRONIZATION

The $\overline{SS}$ pin allows a synchronous slave mode. The SPI must be in slave mode with $\overline{SS}$ pin control enabled (SSPCON<3:0> = 0100). The pin must not be driven low for the $\overline{SS}$ pin to function as an input. TRISA<5> must be set. When the $\overline{SS}$ pin is low, transmission and reception are enabled and the SDO pin is driven. When the $\overline{SS}$ pin goes high, the SDO pin is no longer driven, even if in the middle of a transmitted byte, and becomes a floating output. External pull-up/ pull-down resistors may be desirable, depending on the application.

Note:	When the SPI module is in Slave Mode with $\overline{SS}$ pin control enabled, (SSPCON<3:0> = 0100) the SPI module will reset if the $\overline{SS}$ pin is set to VDD.
Note:	If the SPI is used in Slave Mode with CKE = '1', then $\overline{SS}$ pin control must be enabled.

When the SPI module resets, the bit counter is forced to 0. This can be done by either forcing the $\overline{SS}$ pin to a high level or clearing the SSPEN bit.

To emulate two-wire communication, the SDO pin can be connected to the SDI pin. When the SPI needs to operate as a receiver the SDO pin can be configured as an input. This disables transmissions from the SDO. The SDI can always be left as an input (SDI function) since it cannot create a bus conflict.

FIGURE 8-7: SLAVE SYNCHRONIZATION WAVEFORM

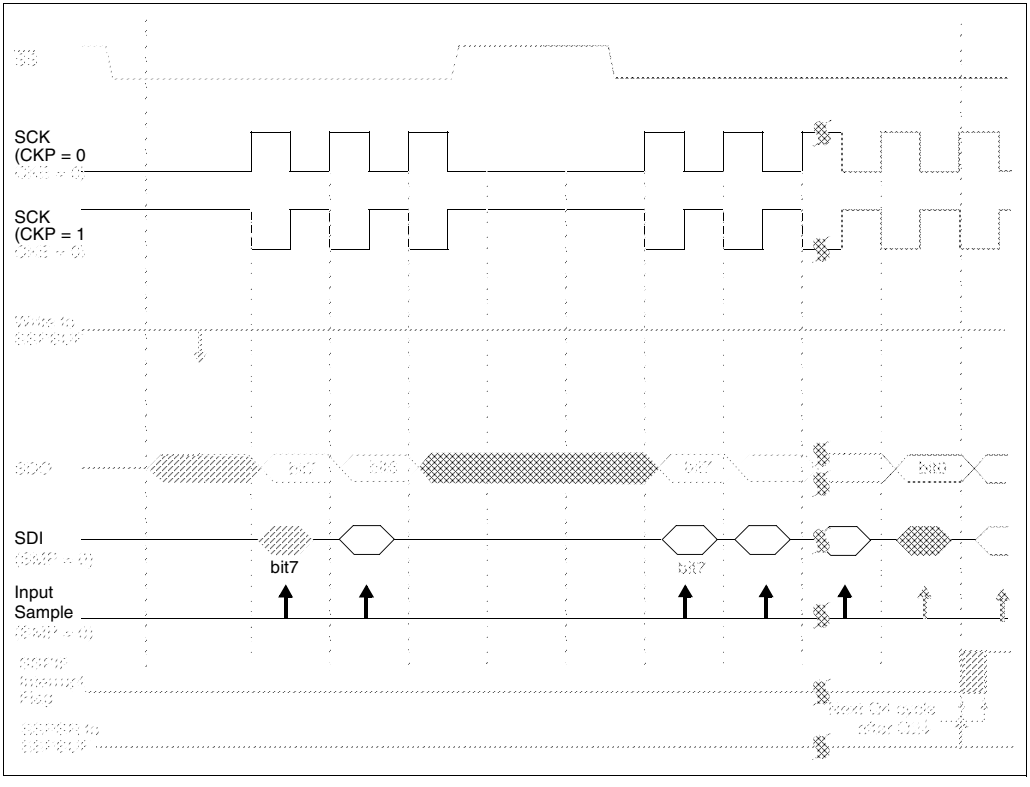
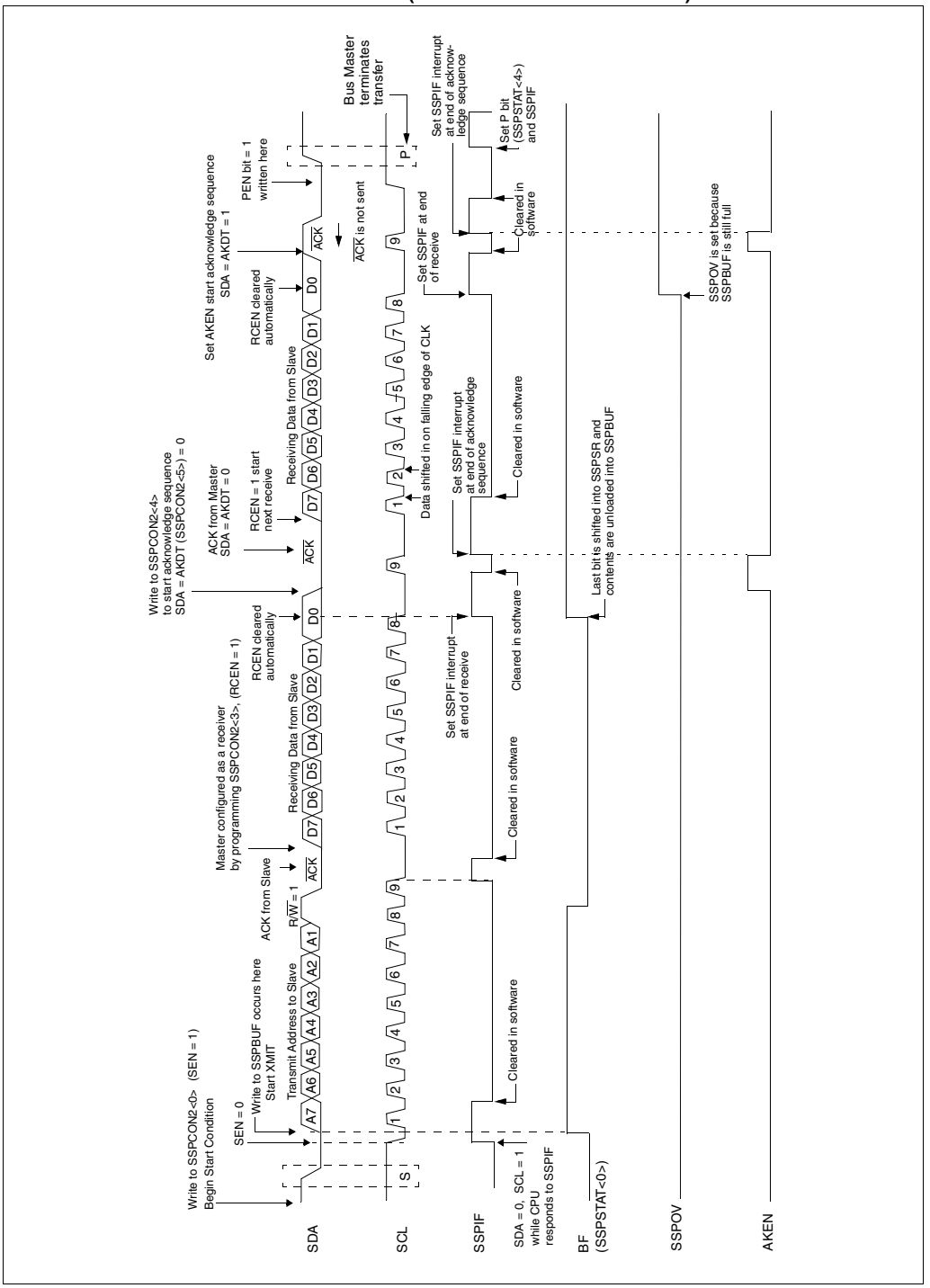


FIGURE 8-28: I²C MASTER MODE TIMING (RECEPTION 7-BIT ADDRESS)



8.2.18.16 BUS COLLISION DURING A REPEATED START CONDITION

During a Repeated Start condition, a bus collision occurs if:

a) A low level is sampled on SDA when SCL goes from low level to high level.

b) SCL goes low before SDA is asserted low, indicating that another master is attempting to transmit a data '1'.

When the user de-asserts SDA and the pin is allowed to float high, the BRG is loaded with SSPADD<6:0>, and counts down to 0. The SCL pin is then de-asserted, and when sampled high, the SDA pin is sampled. If SDA is low, a bus collision has occurred (i.e. another master is attempting to transmit a data '0'). If however SDA is sampled high then the BRG is reloaded and begins counting. If SDA goes from high to low before the BRG times out, no bus collision occurs, because no two masters can assert SDA at exactly the same time.

If, however, SCL goes from high to low before the BRG times out and SDA has not already been asserted, then a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition.

If at the end of the BRG time out both SCL and SDA are still high, the SDA pin is driven low, the BRG is reloaded, and begins counting. At the end of the count, regardless of the status of the SCL pin, the SCL pin is driven low and the Repeated Start condition is complete (Figure 8-38).

FIGURE 8-38: BUS COLLISION DURING A REPEATED START CONDITION (CASE 1)

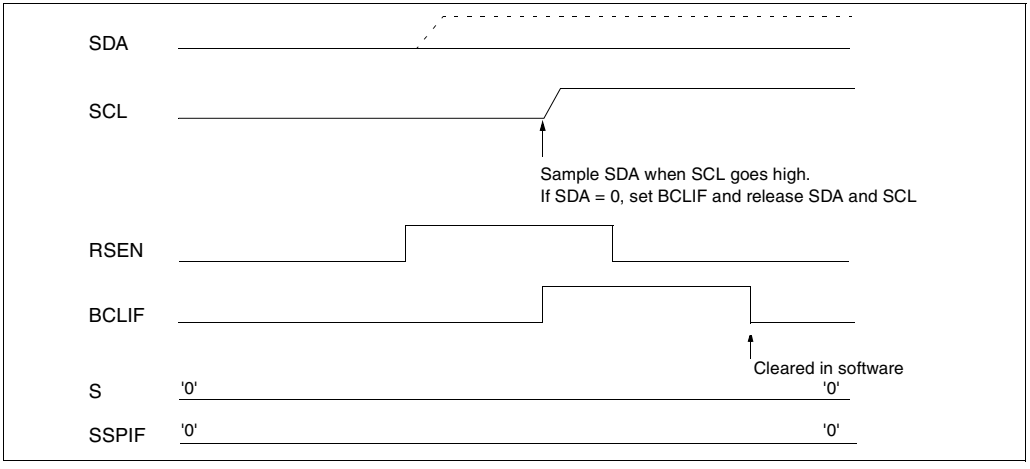


FIGURE 8-39: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)

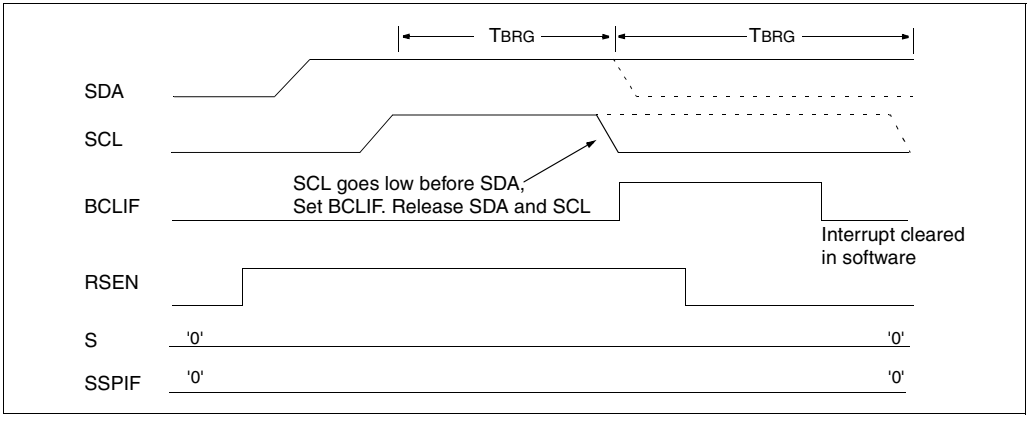


FIGURE 9-4: ASYNCHRONOUS TRANSMISSION

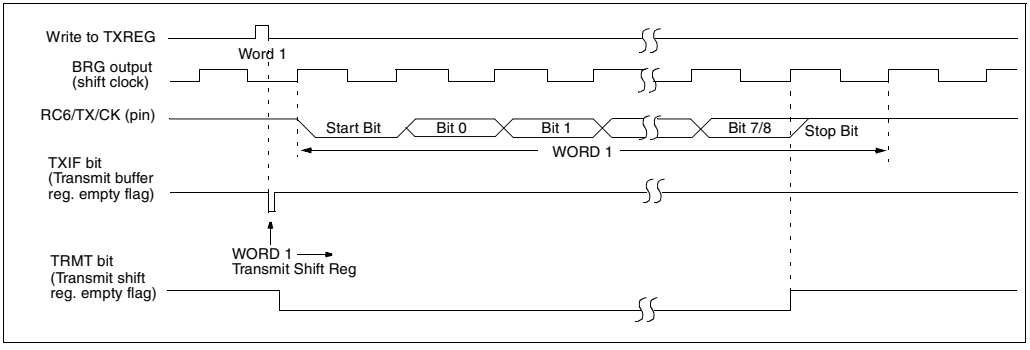
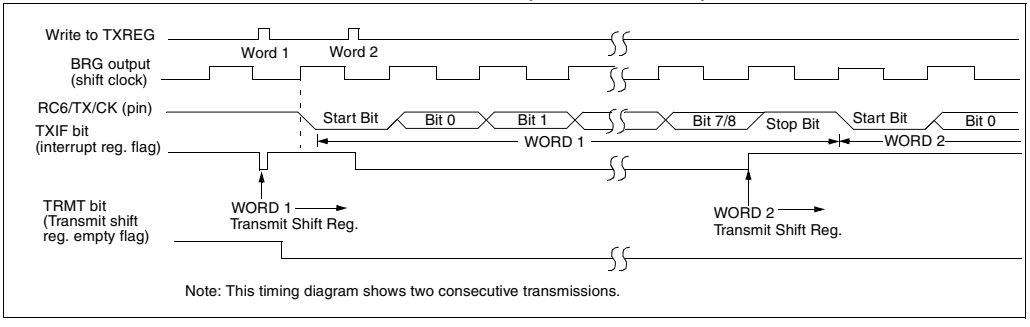


FIGURE 9-5: ASYNCHRONOUS TRANSMISSION (BACK TO BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 9-6 REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
19h	TXREG	USART Transmit Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Asynchronous Transmission.
Note 1: Bits PSPIE and PSPIF are reserved on the 28-pin devices, always maintain these bits clear.

12.10.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if bit INTEDG (OPTION_REG<6>) is set, or falling, if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from SLEEP, if bit INTE was set prior to going into SLEEP. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 12.13 for details on SLEEP mode.

12.10.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>). (Section 4.0)

12.10.3 PORTB INTCON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>). (Section 3.2)

12.11 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt, i.e., W register and STATUS register. This will have to be implemented in software.

Example 12-1 stores and restores the W and STATUS registers. The register, W_TEMP, must be defined in each bank and must be defined at the same offset from the bank base address (i.e., if W_TEMP is defined at 0x20 in bank 0, it must also be defined at 0xA0 in bank 1).

The example:

a) Stores the W register.
b) Stores the STATUS register in bank 0.
c) Stores the PCLATH register.
d) Executes the interrupt service routine code (User-generated).
e) Restores the STATUS register (and bank select bit).
f) Restores the W and PCLATH registers.

EXAMPLE 12-1: SAVING STATUS, W, AND PCLATH REGISTERS IN RAM

```
MOVWF    W_TEMP           ;Copy W to TEMP register, could be bank one or zero
SWAPF    STATUS,W         ;Swap status to be saved into W
CLRF     STATUS           ;bank 0, regardless of current bank, Clears IRP,RP1,RP0
MOVWF    STATUS_TEMP      ;Save status to bank zero STATUS_TEMP register
MOVF     PCLATH, W        ;Only required if using pages 1, 2 and/or 3
MOVWF    PCLATH_TEMP      ;Save PCLATH into W
CLRF     PCLATH           ;Page zero, regardless of current page
BCF      STATUS, IRP      ;Return to Bank 0
MOVF     FSR, W           ;Copy FSR to W
MOVWF    FSR_TEMP         ;Copy FSR from W to FSR_TEMP
:
:(ISR)
:
MOVF     PCLATH_TEMP, W   ;Restore PCLATH
MOVWF    PCLATH           ;Move W into PCLATH
SWAPF    STATUS_TEMP,W    ;Swap STATUS_TEMP register into W
                          ;(sets bank to original state)
MOVWF    STATUS           ;Move W into STATUS register
SWAPF    W_TEMP,F         ;Swap W_TEMP
SWAPF    W_TEMP,W         ;Swap W_TEMP into W
```


14.10 MPLAB Integrated Development Environment Software

The MPLAB IDE Software brings an ease of software development previously unseen in the 8-bit microcontroller market. MPLAB is a windows based application which contains:

- A full featured editor
- Three operating modes
  - editor
  - emulator
  - simulator
- A project manager
- Customizable tool bar and key mapping
- A status bar with project information
- Extensive on-line help

MPLAB allows you to:

- Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PICmicro tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file

The ability to use MPLAB with Microchip's simulator allows a consistent platform and the ability to easily switch from the low cost simulator to the full featured emulator with minimal retraining due to development tools.

14.11 Assembler (MPASM)

The MPASM Universal Macro Assembler is a PC-hosted symbolic assembler. It supports all microcontroller series including the PIC12C5XX, PIC14000, PIC16C5X, PIC16CXXX, and PIC17CXX families.

MPASM offers full featured Macro capabilities, conditional assembly, and several source and listing formats. It generates various object code formats to support Microchip's development tools as well as third party programmers.

MPASM allows full symbolic debugging from MPLAB-ICE, Microchip's Universal Emulator System.

MPASM has the following features to assist in developing software for specific use applications.

- Provides translation of Assembler source code to object code for all Microchip microcontrollers.
- Macro assembly capability.
- Produces all the files (Object, Listing, Symbol, and special) required for symbolic debug with Microchip's emulator systems.
- Supports Hex (default), Decimal and Octal source and listing formats.

MPASM provides a rich directive language to support programming of the PICmicro. Directives are helpful in making the development of your assemble source code shorter and more maintainable.

14.12 Software Simulator (MPLAB-SIM)

The MPLAB-SIM Software Simulator allows code development in a PC host environment. It allows the user to simulate the PICmicro series microcontrollers on an instruction level. On any given instruction, the user may examine or modify any of the data areas or provide external stimulus to any of the pins. The input/output radix can be set by the user and the execution can be performed in; single step, execute until break, or in a trace mode.

MPLAB-SIM fully supports symbolic debugging using MPLAB-C17 and MPASM. The Software Simulator offers the low cost flexibility to develop and debug code outside of the laboratory environment making it an excellent multi-project software development tool.

14.13 MPLAB-C17 Compiler

The MPLAB-C17 Code Development System is a complete ANSI 'C' compiler and integrated development environment for Microchip's PIC17CXXX family of microcontrollers. The compiler provides powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compiler provides symbol information that is compatible with the MPLAB IDE memory display.

14.14 Fuzzy Logic Development System (*fuzzy*TECH-MP)

*fuzzy*TECH-MP fuzzy logic development tool is available in two versions - a low cost introductory version, MP Explorer, for designers to gain a comprehensive working knowledge of fuzzy logic system design; and a full-featured version, *fuzzy*TECH-MP, Edition for implementing more complex systems.

Both versions include Microchip's *fuzzy*LAB™ demonstration board for hands-on experience with fuzzy logic systems implementation.

14.15 SEEVAL® Evaluation and Programming System

The SEEVAL SEEPROM Designer's Kit supports all Microchip 2-wire and 3-wire Serial EEPROMs. The kit includes everything necessary to read, write, erase or program special features of any Microchip SEEPROM product including Smart Serials™ and secure serials. The Total Endurance™ Disk is included to aid in trade-off analysis and reliability calculations. The total kit can significantly reduce time-to-market and result in an optimized system.

14.16 KEELOQ® Evaluation and Programming Tools

KEELOQ evaluation and programming tools support Microchips HCS Secure Data Products. The HCS evaluation kit includes an LCD display to show changing codes, a decoder to decode transmissions, and a programming interface to program test transmitters.

15.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, $\overline{MCLR}$. and RA4) ..... -0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS ..... -0.3 to +7.5V
Voltage on $\overline{MCLR}$ with respect to VSS (Note 2) ..... 0 to +8.5V
Voltage on RA4 with respect to Vss ..... 0 to +8.5V
Total power dissipation (Note 1) 1.0W
Maximum current out of VSS pin ..... 300 mA
Maximum current into VDD pin ..... 250 mA
Input clamp current, IIK (VI < 0 or VI > VDD) ..... ± 20 mA
Output clamp current, IOK (VO < 0 or VO > VDD) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (combined) (Note 3) ..... 200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (combined) (Note 3) ..... 200 mA
Maximum current sunk by PORTC and PORTD (combined) (Note 3) ..... 200 mA
Maximum current sourced by PORTC and PORTD (combined) (Note 3) ..... 200 mA

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - ∑ IOH} + ∑ {(VDD - VOH) x IOH} + ∑(Vol x IOL)

Note 2: Voltage spikes below VSS at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to VSS.

Note 3: PORTD and PORTE are not implemented on the PIC16C773.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 15-1 CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C773-04 PIC16C774-04	PIC16C773-20 PIC16C774-20	PIC16LC773-04 PIC16LC774-04	JW Devices
RC	VDD: 4.0V to 5.5V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 5.5V IDD: 3.8 mA max. at 3.0V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 5.5V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 5.5V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 5.5V IDD: 3.8 mA max. at 3.0V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 5.5V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.	Not tested for functionality	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 5.5V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Not tested for functionality	VDD: 2.5V to 5.5V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5.0 μA max. at 3.0V Freq: 200 kHz max.	VDD: 2.5V to 5.5V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5.0 μA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications.
It is recommended that the user select the device type that ensures the specifications required.

FIGURE 15-2: BROWN-OUT RESET CHARACTERISTICS

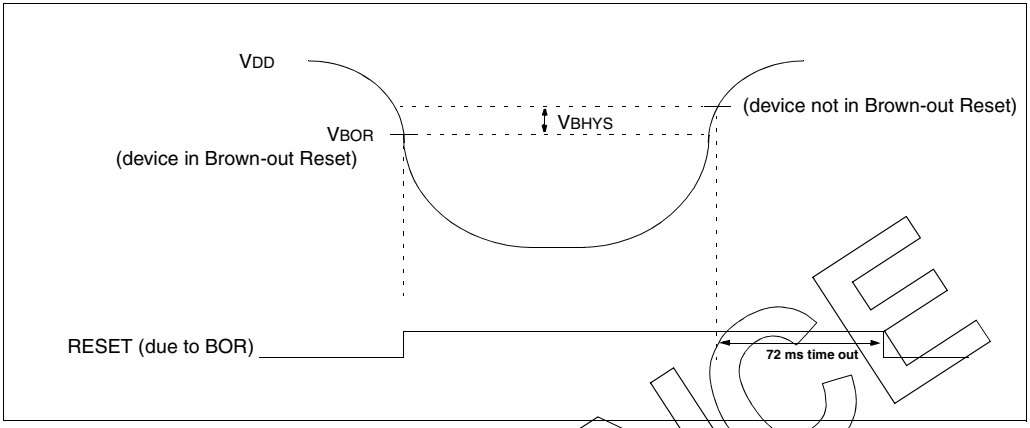


TABLE 15-4 ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS								
	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 15.1 and Section 15.2.							
Param No.	**Characteristic**		**Symbol**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
D005	BOR Voltage	BORV1:0 = 11	VBOR	2.5	2.58	2.66	V	
		BORV1:0 = 10		2.7	2.78	2.86		
		BORV1:0 = 01		4.2	4.33	4.46		
		BORV1:0 = 00		4.5	4.64	4.78		
D006*	BOR Voltage Drift Temperature coefficient		TCVOUT	—	15	50	ppm/°C	
D006A*	BOR Voltage Drift with respect to VDD Regulation		ΔVBOR/ ΔVDD	—	—	50	μV/V	
D007	Brown-out Hysteresis		VBHYS	TBD	—	100	mV	
D022A	Supply Current		ΔIBOR	—	10	20	μA	

* These parameters are characterized but not tested.

Note 1: Production tested at TAMB = 25°C. Specifications over temp limits ensured by characterization.

FIGURE 15-12: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)

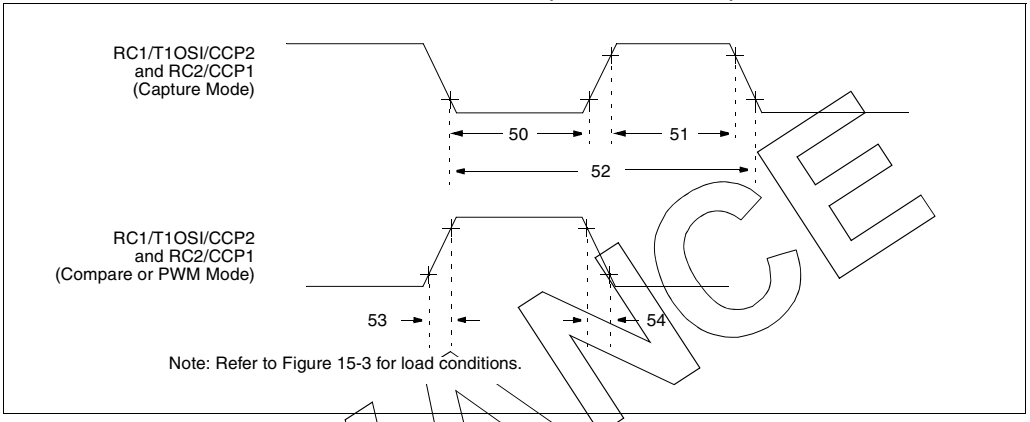


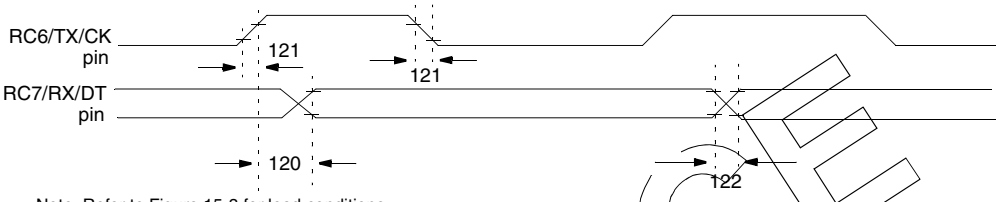
TABLE 15-13 CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Parameter No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**77X	10	—	—	ns	
				PIC16**LC**77X	20	—	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	PIC16**C**77X	10	—	—	ns	
				PIC16**LC**77X	20	—	—	ns	
52*	TccP	CCP1 and CCP2 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)
53*	TccR	CCP1 and CCP2 output fall time		PIC16**C**77X	—	10	25	ns	
				PIC16**LC**77X	—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time		PIC16**C**77X	—	10	25	ns	
				PIC16**LC**77X	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-14: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



Note: Refer to Figure 15-3 for load conditions.

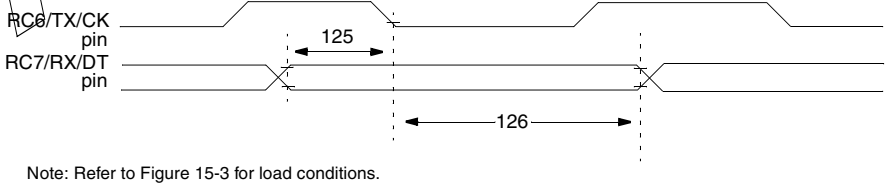
TABLE 15-15 USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
120*	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	PIC16**C**774/773	—	—	80	ns	
			PIC16**LC**774/773	—	—	100	ns	
121*	Tckrf	Clock out rise time and fall time (Master Mode)	PIC16**C**774/773	—	—	45	ns	
			PIC16**LC**774/773	—	—	50	ns	
122*	Tdtrf	Data out rise time and fall time	PIC16**C**774/773	—	—	45	ns	
			PIC16**LC**774/773	—	—	50	ns	

* These parameters are characterized but not tested.

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-15: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 15-3 for load conditions.

TABLE 15-16 USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125*	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126*	TckL2dtl	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

* These parameters are characterized but not tested.

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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